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FEATURES

- Bidirectional Voltage Translator
- 5.5 V on A Port and 2.7 V to 3.6 V on B Port
- Control Inputs V_{IH}/V_{IL} Levels Are Referenced to V_{CCA} Voltage
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

DESCRIPTION/ORDERING INFORMATION

This 8-bit (octal) noninverting bus transceiver contains two separate supply rails; B port has V_{CCB} , which is set at 3.3 V, and A port has V_{CCA} , which is set at 5 V. This allows for translation from a 3.3-V to a 5-V environment, and vice versa.

DB, DW, OR PW PACKAGE (TOP VIEW) (5 V) V_{CCA} L 24 V_{CCB} (3.3 V) DIR 2 23 V_{CCB} (3.3 V) A1 [22 OE 21 B1 A2 [A3 **∏** 5 20 **∏** B2 19**∏** B3 A4 l 6 A5 [7 18**∏** B4 A6 ∏ 8 17**∏** B5 9 16 B6 A7 L 15**∏** B7 А8 Г 10 GND **1**11 14**∏** B8 GND [] 12 13 | GND

The SN74LVC4245A is designed for asynchronous communication between data buses. The device transmits data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so the buses are effectively isolated. The control circuitry (DIR, \overline{OE}) is powered by V_{CCA} .

The SN74LVC4245A pinout allows the designer to switch to a normal all-3.3-V or all-5-V 20-pin '245 device without board re-layout. The designer uses the data paths for pins 2–11 and 14–23 of the SN74LVC4245A to align with the conventional '245 pinout.

ORDERING INFORMATION

T _A	PACKAGE ⁽¹⁾		PACKAGE ⁽¹⁾ ORDERABLE PART NUMBER	
	SOIC - DW	Tube of 25	SN74LVC4245ADW	LVC4245A
	SOIC - DW	Reel of 2000	SN74LVC4245ADWR	LVC4245A
–40°C to 85°C	SSOP - DB	Reel of 2000	SN74LVC4245ADBR	LJ245A
-40 C to 65 C		Tube of 60	SN74LVC4245APW	
	TSSOP - PW	Reel of 2000	el of 2000 SN74LVC4245APWR LJ24	
	F	Reel of 250	SN74LVC4245APWT	

⁽¹⁾ Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

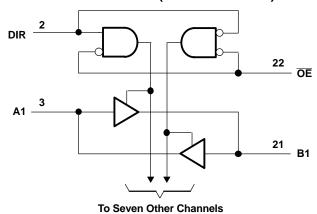
INP	UTS	ODEDATION		
ŌĒ	DIR	OPERATION		
L	L	B data to A bus		
L	Н	A data to B bus		
Н	Χ	Isolation		



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LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range for $V_{CCA} = 4.5 \text{ V}$ to 5.5 V (unless otherwise noted)

			MIN	MAX	UNIT	
V_{CCA}	Supply voltage range		-0.5	6.5	V	
	lanut valtaga ranga	A port ⁽²⁾	-0.5	V _{CCA} + 0.5	V	
V _I	Input voltage range	Control inputs	-0.5	6	V	
Vo	Output voltage range	A port ⁽²⁾	-0.5	V _{CCA} + 0.5	V	
I _{IK}	Input clamp current	V _I < 0		-50	mA	
I _{OK}	Output clamp current	V _O < 0		-50	mA	
Io	Continuous output current			±50	mA	
	Continuous current through each V _{CCA} or G	SND		±100	mA	
		DB package		63		
θ_{JA}	Package thermal impedance (3)	DW package		46	6 °C/W	
		PW package		88		
T _{stg}	Storage temperature range		-65	150	°C	

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

⁽²⁾ This value is limited to 6 V maximum.

⁽³⁾ The package thermal impedance is calculated in accordance with JESD 51-7.



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Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range for $V_{CCB} = 2.7 \text{ V}$ to 3.6 V (unless otherwise noted)

			MIN	MAX	UNIT
V_{CCB}	Supply voltage range		-0.5	4.6	V
VI	Input voltage range	B port ⁽²⁾	-0.5	V _{CCB} + 0.5	V
Vo	Output voltage range	B port ⁽²⁾	-0.5	V _{CCB} + 0.5	V
I _{IK}	Input clamp current	V _I < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
Io	Continuous output current			±50	mA
	Continuous current through V _{CCB} or GND			±100	mA
		DB package		63	
θ_{JA}	Package thermal impedance (3)	DW package		46	°C/W
		PW package		88	
T _{stg}	Storage temperature range		-65	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

Recommended Operating Conditions⁽¹⁾

for $V_{CCA} = 4.5 \text{ V}$ to 5.5 V

		MIN	MAX	UNIT
V_{CCA}	Supply voltage	4.5	5.5	V
V _{IH}	High-level input voltage	2		V
V _{IL}	Low-level input voltage		0.8	V
V _{IA}	Input voltage	0	V_{CCA}	V
V _{OA}	Output voltage	0	V_{CCA}	V
I _{OH}	High-level output current		-24	mA
I _{OL}	Low-level output current		24	mA
T _A	Operating free-air temperature	-40	85	°C

⁽¹⁾ All unused inputs of the device must be held at the associated V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

Recommended Operating Conditions⁽¹⁾

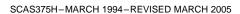
for $V_{CCB} = 2.7 \text{ V}$ to 3.6 V

			MIN	MAX	UNIT
V_{CCB}	Supply voltage		2.7	3.6	V
V_{IH}	High-level input voltage	V _{CCB} = 2.7 V to 3.6 V	2		V
V_{IL}	Low-level input voltage	V _{CCB} = 2.7 V to 3.6 V		0.8	V
V_{IB}	Input voltage	0	V _{CCB}	V	
V_{OB}	Output voltage		0	V_{CCB}	V
	High-level output current	V _{CCB} = 2.7 V		-12	mA
ЮН	nigir-ievei output current	V _{CCB} = 3 V		-24	ША
	Low lovel output ourrent	V _{CCB} = 2.7 V		12	mΛ
IOL	Low-level output current $V_{CCB} = 3 \text{ V}$			24	mA
T_A	Operating free-air temperature	·	-40	85	°C

⁽¹⁾ All unused inputs of the device must be held at the associated V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

⁽²⁾ This value is limited to 4.6 V maximum.

⁽³⁾ The package thermal impedance is calculated in accordance with JESD 51-7.





Electrical Characteristics(1)

over recommended operating free-air temperature range for $V_{CCA} = 4.5 \text{ V}$ to 5.5 V (unless otherwise noted)

PA	RAMETER	TEST CONDITIONS	V _{CCA}	MIN TYP ⁽²⁾	MAX	UNIT
		100	4.5 V	4.3		
\/		$I_{OH} = -100 \mu A$	5.5 V	5.3		V
V _{OH}		1 24 mA	4.5 V	3.7		V
		$I_{OH} = -24 \text{ mA}$	5.5 V	4.7		
		L = 100 uA	4.5 V		0.2	
\/		I _{OL} = 100 μA	5.5 V		0.2	V
V _{OL}		24 m A	4.5 V		0.55	V
		I _{OL} = 24 mA	5.5 V		0.55	
I	Control inputs	V _I = V _{CCA} or GND	5.5 V		±1	μΑ
$I_{OZ}^{(3)}$	A port	$V_O = V_{CCA}$ or GND	5.5 V		±5	μΑ
I_{CCA}		$V_I = V_{CCA}$ or GND, $I_O = 0$	5.5 V		80	μΑ
$\Delta I_{CCA}^{(4)}$		One input at 3.4 V, Other inputs at V _{CCA} or GI	ND 5.5 V		1.5	mA
C _i	Control inputs	V _I = V _{CCA} or GND	Open	5		pF
C _{io}	A port	$V_O = V_{CCA}$ or GND	5 V	11		pF

Electrical Characteristics(1)

over recommended operating free-air temperature range for V_{CCB} = 2.7 V to 3.6 V (unless otherwise noted)

PARA	PARAMETER TEST CONDITIONS		ONDITIONS	V _{CCB}	MIN	TYP ⁽²⁾	MAX	UNIT
		$I_{OH} = -100 \mu A$		2.7 V to 3.6 V	V _{CC} - 0.2			
\/		l – 12 mΛ		2.7 V	2.2			V
V _{OH}		$I_{OH} = -12 \text{ mA}$		3 V	2.4			v
		$I_{OH} = -24 \text{ mA}$	3 V	2				
		I _{OL} = 100 μA		2.7 V to 3.6 V			0.2	
V_{OL}		I _{OL} = 12 mA		2.7 V			0.4	V
		I _{OL} = 24 mA		3 V			0.55	
I _{OZ} (3)	B port	$V_O = V_{CCB}$ or GND		3.6 V			±5	μΑ
I _{CCB}		$V_I = V_{CCB}$ or GND,	$I_{O} = 0$	3.6 V			50	μΑ
$\Delta I_{CCB}^{(4)}$		One input at V _{CCB} – 0.6 V,	Other inputs at V _{CCB} or GND	2.7 V to 3.6 V			0.5	mA
C _{io}	B port	$V_O = V_{CCB}$ or GND		3.3 V		11		pF

 V_{CCB} = 2.7 V to 3.6 V All typical values are measured at V_{CC} = 5 V, T_A = 25°C. For I/O ports, the parameter I_{OZ} includes the input leakage current. This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or the associated V_{CC}

 ⁽¹⁾ V_{CCA} = 5 V ± 0.5 V
(2) All typical values are measured at V_{CC} = 3.3 V, T_A = 25°C.
(3) For I/O ports, the parameter I_{OZ} includes the input leakage current.
(4) This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or the associated ...



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Switching Characteristics

over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1 and Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCA} = 5 V \pm V_{CCB} = 2.7 V t$	UNIT	
	(INFOT)	(001F01)	MIN	MAX	
t _{PHL}	A	В	1	6.3	20
t _{PLH}	A	В	1	6.7	ns
t _{PHL}	В	A	1	6.1	nc
t _{PLH}	Б	A	1	5	ns
t _{PZL}	ŌĒ	A		9	20
t _{PZH}	OE .	A	1	8.1	ns
t _{PZL}	ŌĒ	В	1	8.8	ns
t _{PZH}	OE .	В	1	9.8	115
t _{PLZ}	ŌĒ	A	1	7	20
t _{PHZ}	OE .	A	1	5.8	ns
t _{PLZ}	ŌĒ	В	1	7.7	20
t _{PHZ}	JE	В	1	7.8	ns

Operating Characteristics

 V_{CCA} = 4.5 V to 5.5 V, V_{CCB} = 2.7 V to 3.6 V, T_A = 25°C

	PARAMETER			ONDITIONS	TYP	UNIT
	Dower dissinction constitutes not transcriver	Outputs enabled	C 0	f 40 MHz	39.5	, L
C_{pd}	Power dissipation capacitance per transceiver	Outputs disabled	$C_L = 0$,	f = 10 MHz	5	pF

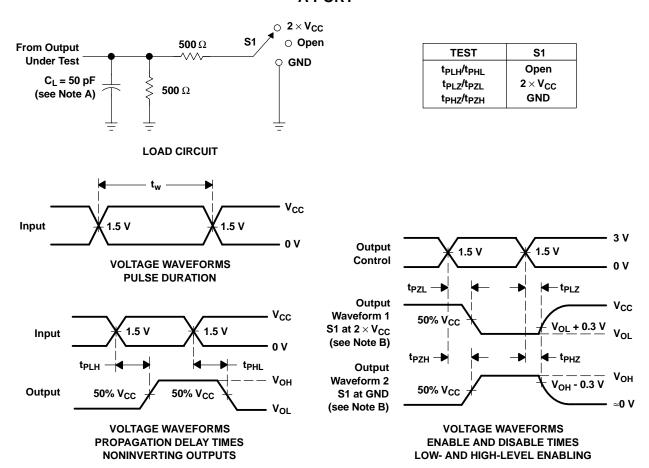
Power-Up Considerations(1)

TI level-translation devices offer an opportunity for successful mixed-voltage signal design. A proper power-up sequence always should be followed to avoid excessive supply current, bus contention, oscillations, or other anomalies caused by improperly biased device pins. Take these precautions to guard against such power-up problems:

- 1. Connect ground before any supply voltage is applied.
- 2. Power up the control side of the device (V_{CCA} for all four of these devices).
- 3. Tie \overline{OE} to V_{CCA} with a pullup resistor so that it ramps with V_{CCA} .
- 4. Depending on the direction of the data path, DIR can be high or low. If DIR high is needed (A data to B bus), ramp it with V_{CCA} . Otherwise, keep DIR low.
- (1) Refer to the TI application report, Texas Instruments Voltage-Level-Translation Devices, literature number SCEA021.



PARAMETER MEASUREMENT INFORMATION A PORT



NOTES: A. C_L includes probe and jig capacitance.

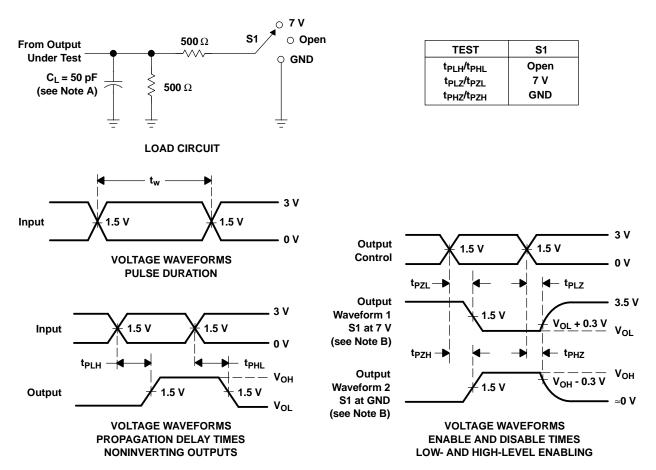
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{O} = 50 Ω , $t_{f} \leq$ 2.5 ns, $t_{f} \leq$ 2.5 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



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PARAMETER MEASUREMENT INFORMATION B PORT



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{O} = 50 Ω , $t_{f} \leq$ 2.5 ns, $t_{f} \leq$ 2.5 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms





i.com 6-Jun-2005

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LVC4245ADBR	ACTIVE	SSOP	DB	24	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74LVC4245ADBRE4	ACTIVE	SSOP	DB	24	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74LVC4245ADW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC4245ADWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC4245ADWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC4245ADWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC4245APW	ACTIVE	TSSOP	PW	24	60	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74LVC4245APWG4	ACTIVE	TSSOP	PW	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC4245APWR	ACTIVE	TSSOP	PW	24	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74LVC4245APWRG4	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC4245APWT	ACTIVE	TSSOP	PW	24	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74LVC4245APWTE4	ACTIVE	TSSOP	PW	24	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DW (R-PDSO-G24)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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